

AGENDA

Soldering Technology Committee (STC) April 29, 2009 Chateau Bourbon – New Orleans

1) Introductions and Roster modifications

2) October 2008 meeting minutes approval

2 Old business

3 New business

3.1 Revision to IPC/EIA J-STD-002

3.1.1 Alignment of J-STD-002 and JEDEC B102

Latest Status:

- Dave Hillman has summarized differences between JSTD-002/B102.
- Paul Melville has provided a summary of JEDEC JC14.1 inputs on JSTD-002.
- A conference call is scheduled for first week of May between Romm, Hillman, Russell and Melville to initiate activity on standards alignment.
- Input from Mr. Melville is "The JEDEC position remains that JESD22-B102 will be rescinded and replaced by J-STD-002 after these issues are resolved."

3.2 Possible replacements for steam pre-conditioning

Status of the DOE will be discussed.

- Excel file provided is Dip-and-Look data – 1 facility
- Two facilities are performing Wetting Balance (RIM, Bev Christian, STS, Gerard O'Brien)
- One facility is performing assembly processing (Rockwell-Collins, Hillman)
- Data will be reviewed by next meeting of IPC (Sept 21st Fall) and STC (Fall)
- We also have final auger results, Dave to send.
- Assembly processed units will be judged for visual wetting per J-STD-002; flux is ROL0 rosin based no activation, most conservative.
- Intent would be to use the assembly data to scale where we need to be on the solderability test.

3.3 Gauge R&R for wetting balance test

The wetting balance test method is currently listed in ANSI/J-STD-002 under the section "Tests without Established Accept/Reject Criterion". Input from Dave Hillman was that the IPC committee discussed the options of either validating or removing the wetting balance method as an accepted method. Team needs to discuss plans/timing for future work.

4 Next meeting

5 Adjournment